

# ASDAM '26



Advanced Semiconductor Devices and Microsystems

**7 – 9 October 2026**  
**RADISSON BLU CARLTON HOTEL**  
**BRATISLAVA, SLOVAKIA**

**16th International Conference on**  
**Advanced Semiconductor**  
**Devices and Microsystems**

## IMPORTANT DATES:

1.4.2026	<b>Start abstract submission</b>
1.6.2026	<b>Abstract submission deadline</b>
30.6.2026	<b>Abstract confirmation notification</b>
14.8.2026	<b>Full paper submission</b>
Up to 14.8.2026	<b>Early registration</b>
From 15.8.2026	<b>Late registration</b>

**ASDAM 2026 will be devoted to the latest results of research and development in the field of new semiconductor devices and microsystems.**

Leading experts from institutes and universities as well as companies interested in the progress of high technology devices and microsystems will meet in Bratislava.

The Conference Proceedings will be published by the IEEE Electron Devices Society.

The official language of the Conference is English. The Conference is opened for presentation of semiconductor materials and instrumentation used in device development and production. Conditions and details will be sent by the organizer upon request. The ASDAM Conference will take place in Radisson Blu Carlton in Bratislava. The conference venue, Radisson Blu Carlton Hotel, Bratislava, is set in the historic centre of Bratislava, overlooking Hviezdoslav Square and offering easy access to the city's main cultural landmarks.

Invited and contributed papers (oral and poster presentations) will be published in the Conference Proceedings (IEEE Xplore indexed in WoS)  
[www.asdam.sk](http://www.asdam.sk)

Authors are encouraged to submit the abstract (in pdf format) electronically to [asdam@skchips.sk](mailto:asdam@skchips.sk)

Further information: [www.asdam.sk](http://www.asdam.sk)

## SCOPE OF THE CONFERENCE

### Materials and Technologies

- WBG and UWBG materials
- Semiconductor and dielectric materials
- 2D Materials and Nanostructures
- Organic electronics
- Structures and Devices

### WBG, UWBG planar, vertical, and heterostructure devices

- III-V, Nitrides, Oxides, Carbides, diamond
- Power and microwave electronic devices and systems
- Quantum heterostructures devices
- Neuromorphic devices
- Packaging technologies

### Characterization, Modelling and Simulation

- 2-D and 3-D process, structure, and device simulation
- Multiphysics simulations
- Structural, optical, electrical, and defect characterization
- Reliability evaluation and modelling

### Sensors and Microsystems

- Design and fabrication
- Surface and bulk micromachining
- MEMS, NEMS structures and devices
- SMART Sensors

### Photonics

- Lasers and photodetectors
- Waveguides, gratings, splitters
- Quantum sensing and computing

### Related topics

- Advanced Energy Storage Materials & Devices
- Advances in IO design

Organized by:

